FLIP CHIP IN LEADED MOLDED PACKAGE WITH TWO DIES

ABSTRACT OF THE DISCLOSURE

A chip device including two stacked dies. The chip device includes a leadframe that includes a plurality of leads. A first die is coupled to a first side of the leadframe with solder and a second die is coupled to a second side of the leadframe with solder. A molded body surrounds at least a portion of the leadframe and the dies.

SF 1107139 v1